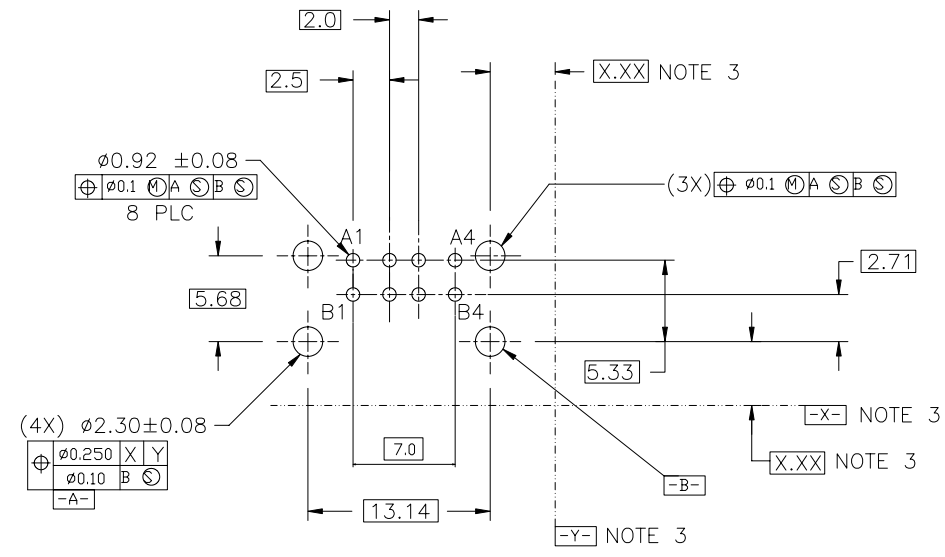
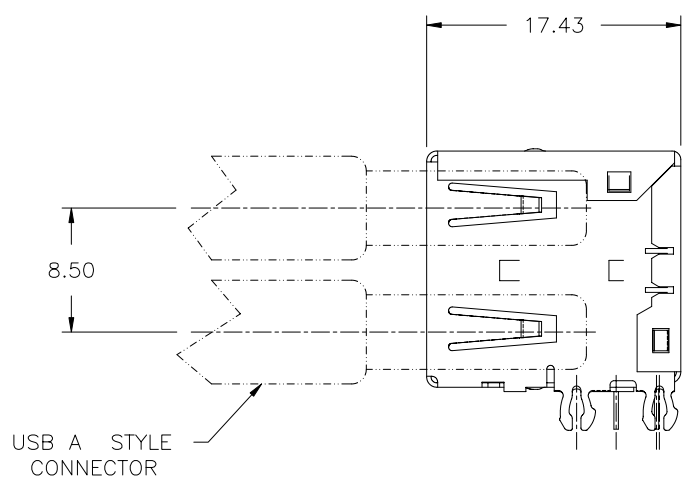


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PRODUCT NUMBER
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RECOMMENDED PC DIMENSIONS

NOTES:

- 1.MATERIAL:
CONTACTS; COPPER ALLOY.
SHELL; COPPER ALLOY.
HOUSING; THERMOPLASTIC, UL 94-V0 RATING
- 2.PLATING:
TERMINALS CONTACT AREA: 0.76um MINIMUM GXT (GOLD FLASH OVER 0.76um PALLADIUM NICKEL)
SOLDER TAIL AREA: GOLD FLASH
UNDERPLATING; 1.27um NICKEL ALL OVER
SHELL; 2.5um MINIMUM BRIGHT TIN/LEAD FOR 52454-X000B AND PURE TIN FOR 52454-X000BLF
UNDERPLATING; 1.27um NICKEL ALL OVER
CENTER GROUND; 2.5um MINIMUM NICKEL
- ③DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
- 4.RECOMMENDED PC BOARD THICKNESS OF 1.57mm.
- 5.PRODUCT NUMBER- SEE PRODUCT NUMBER CODE.
- 6.DIELECTRIC WITHSTANDING VOLTAGE 125VDC
- 7. P/N'S WITH SUFFIX "LF" ARE LEAD FREE P/N'S
- 8. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S
- 9. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008
- 10. FOR LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TERMERATURE FOR 40 SECONDS IN A CONVECTION, INFRO-RED OR VAPOR PHASE REFLOW OVEN.

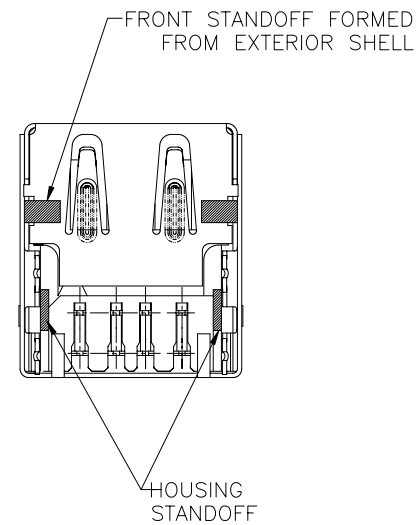
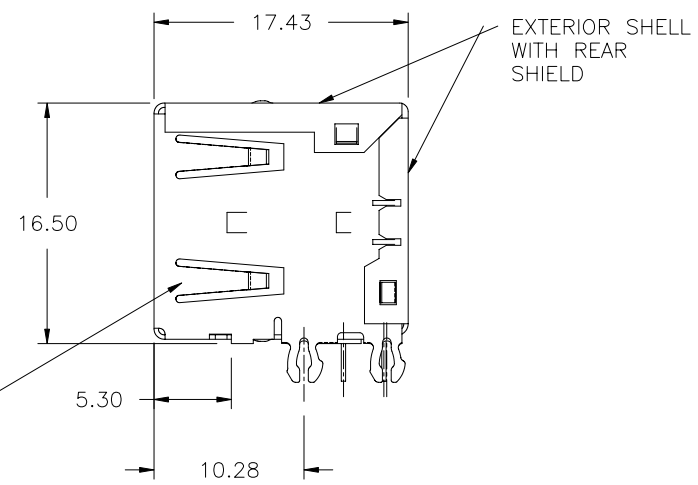
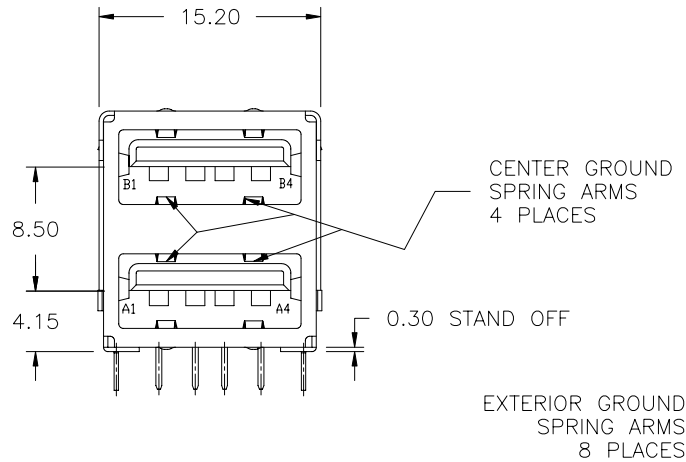
mat'l. code SEE NOTE 1				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com		title USB D/D ASSEMBLY	
ltr	ecn no	dr	date	linear	.X ±.3					
A	T90366	PP	10/25/99		.XX ±.20		projection 	product family size	USB dwg no	code 213
B	T20162	WL	05/20/02		.XXX ±.100					
C	N05-0079	PH	03/21/05	angles	0° ±2°	scale 2 : 1		A	52454	sheet 1 of 3
				dr	PETER	9/28/99				
				enrg	R Y LIU	9/28/99				
				chr	R Y LIU	9/28/99				
				appd	J. TSAO	9/28/99				
sheet index	revision sheet	C	C	C						
		1	2	3						

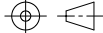
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mat'l. code SEE NOTE 1				tolerances unless otherwise specified			CUSTOMER COPY		A FCI www.fciconnect.com		
ltr	ecn no	dr	date	linear	.X ±.3			projection 	title USB D/D ASSEMBLY		
C					.XX ±.20						
					.XXX ±.050						
				angles	0° ±2°			mm ← → scale 2:1	product family USB size dwg no A 52454		
				dr	PETER	9/28/99					
				engr	R Y LIU	9/28/99					
				chr	R Y LIU	9/28/99					
				appd	J. TSAO	9/28/99					
sheet index		revision sheet									

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SEE PRODUCT NUMBER CODE

52454 - X 0 0 X B LF

LEAD FREE OPTION

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Printed: Oct 21, 2008